

**REPLY UNDER 37 CFR §1.116**  
**EXPEDITED PROCEDURE**  
**TECHNOLOGY CENTER 2800**

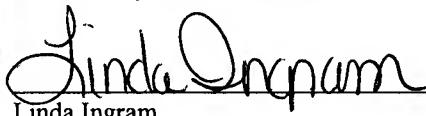
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:	§	Attorney Docket No.
Hsien-Wei Chen, et al.	§	2003-1410 / 24061.193
Serial No.: 10/801,475	§	Customer No. 42717
Filed: March 16, 2004	§	Group Art Unit: 2822
For: SYSTEM FOR HEAT	§	Examiner: Monica Lewis
DISSIPATION IN	§	
SEMICONDUCTOR DEVICES	§	Confirmation No.: 1783

**Mail Stop AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

I hereby certify that this correspondence (including any listed enclosures) is being electronically filed in the United States Patent and Trademark Office via the EFS-Web system on October 9, 2007.

  
Linda Ingram

**RESPONSE UNDER 37 C.F.R. §1.116**

This Response is submitted in reply to the Office Action mailed on September 14, 2007.  
(Please see the pages that follow).